



Connectors > Socket Connectors > IC & Component Socket Accessories > IC Socket Hardware > LGA 2011 Hardware: ILM Assembly



Compatible With IC Socket Type: LGA 2011

Card & Socket Accessory Type: Backplate

Operating Temperature Range: -25 – 100 °C [-13 – 212 °F]

[All LGA 2011 Hardware: ILM Assembly \(0\)](#)

Features

Product Type Features

| | |
|---------------------------------|-----------|
| Socket Connector Accessory Type | Accessory |
| Card & Socket Accessory Type | Backplate |

Body Features

| | |
|----------------------------------|------------------------------------------------|
| Spring Plate Assembly Material | Stainless Steel |
| Top Support Plate Material | Stainless Steel |
| Backplate Material | Steel |
| Primary Product Plating Material | Nickel |
| Insulator Material | Polycarbonate Film Plus Acrylic Adhesive Layer |

Contact Features

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|--------------------------------|----------|
| Compatible With IC Socket Type | LGA 2011 |
|--------------------------------|----------|

Usage Conditions

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|-----------------------------|-------------------------------|
| Operating Temperature Range | -25 – 100 °C [-13 – 212 °F] |
|-----------------------------|-------------------------------|

Packaging Features

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|------------------|---------|
| Packaging Method | Bag/Box |
|------------------|---------|

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

| | |
|-----------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------|
| EU RoHS Directive 2011/65/EU | Compliant |
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JAN 2021 (211) Does not contain REACH SVHC |
| Halogen Content | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free |
| Solder Process Capability | Not applicable for solder process capability |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Documents

Product Drawings

BP ASSY, LGA2011

English



CAD Files

Customer View Model

[ENG_CVM_CVM_2134440-1_B.2d_dxf.zip](#)

English

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_2134440-1_B.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2134440-1_B.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

[6-1773461-9_LGA_2011_SOCKET](#)

English

Product Specifications

[Application Specification](#)

English